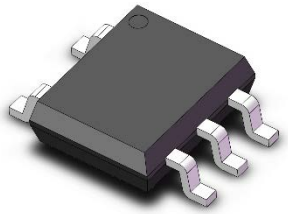
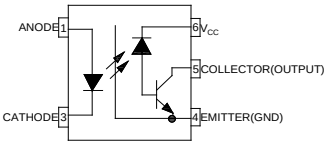
JOC501

Rev.A.1.0

DESCRIPTION:

The products are 1MBd high-speed opto-couplers. The device is a small-outline coupler suitable for surface-mount assembly. It consists of a high-output-power infrared LED optically coupled to a high-speed photodiode-transistor chip. It is housed in the SOP5 package and guarantees a creepage distance of ≥5 mm, a clearance of ≥5 mm and an insulation thickness of ≥0.4 mm. Therefore, it meets the reinforced insulation class requirements of international safety standards. The products are widely used in programmable controllers, industrial inverters and switching power supplies.





MAIN FEATURES

High isolation 3750 VRMS
High speed – 1MBd typical
Operating temperature range -40°C to 110°C
REACH & RoHS compliance
HBM: H3A; MM: M4; CDM: C3
CQC approved
VDE approved
UL approved

Truth Table

LED	Output
ON	L
OFF	H

ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Parameter		Symbol	Value	Unit
Input	Forward Current	I_F	50	mA
	Peak Forward Current	I_{FP}	1①	A
	Reverse Voltage	V_R	6	V
	Input Power Dissipation	P_D	100	mW
Output	Supply Voltage	V_{CC}	35	V
	Output Voltage	V_O	20	V

	Output Current	I_O	8	mA
	Output Power Dissipation	P_O	100	mW
Total Power Dissipation		P_{tot}	200	mW
Isolation Voltage		V_{iso}	3750②	Vrms
Operating Temperature		T_{opr}	-40~110	℃
Junction Temperature		T_j	125	℃
Storage Temperature		T_{stg}	-55~125	℃
Soldering Temperature		T_{sol}	260	℃

NOTE1: 100μs pulse, 100Hz frequency

NOTE2: AC for 1minute, R.H.=40~60%

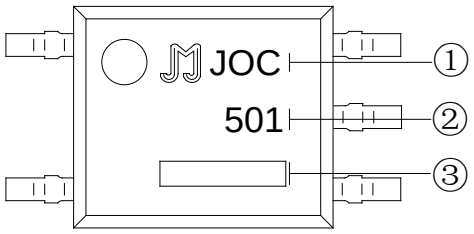
ELECTRICAL CHARACTERISTICS (Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	I_F=10mA	-	1.35	1.6	V
	Reverse Current	I_R	V_R=6V	-	-	1	μA
	Input Capacitance	C_{in}	V=0, f=1MHz	-	60	-	pF
Output	Current transfer ratio	CTR	I_F=16mA, V_{CC}=4.5V, V_O=0.4V	20	-	60	%
	High Level Output Current	I_{OH}	I_F=0mA, V_{CC}=5.5V, V_O=5.5V	-	3	500	nA
			I_F=0mA, V_{CC}=15V, V_O=15V	-	-	50	μA
	Low Level Supply Current	I_{CCL}	V_O=Open, V_{CC}=15V, I_F=16mA	-	0.5	0.8	mA
	High Level Supply Current	I_{CCH}	V_O=Open, V_{CC}=15V, I_F=0mA	-	0.01	2	μA
	Logic Low Output Voltage	V_{OL}	I_F=16mA, I_O=2.4mA, V_{CC}=4.5V	-	-	0.4	V
	Isolation Resistance	R_{ISO}	DC500V 40~60%R.H.	10^{12}	10^{14}	-	Ω
	Floating Capacitance	C_{IO}	V=0, f=1MHz	-	0.8	-	pF
Switching Characteristics	Propagation Delay Time to Logic Low	TPHL	I_F=0→16mA, R_L=1.9kΩ, V_{CC}=5V	-	-	0.8	μs
	Propagation Delay Time to Logic High	TPLH	I_F=16→0mA, R_L=1.9kΩ, V_{CC}=5V	-	-	0.8	μs

	Common Mode Transient Immunity at Logic High	CM_H	I_F=0mA, V_{CM}=400Vpp, R_L=4.1kΩ	15	20	-	kV/μs
	Common Mode Transient Immunity at Logic Low	CM_L	I_F=16mA, V_{CM}=400Vpp, R_L=4.1kΩ	-15	-20	-	kV/μs

ORDERING AND MARKING INFORMATION

MARKING INFORMATION



① : Company Abbr.
② : Part Number & Rank
③ : Production Information Code

Packing Quantity

Option	Quantity	Quantity – Inner box	Quantity –Outer box
SOP5	3000 Units/Reel	2 Reels/Inner box	5 Inner box/Outer box =30k Units

Characteristics Curves

FIG.1: Forward Current vs. Forward Voltage

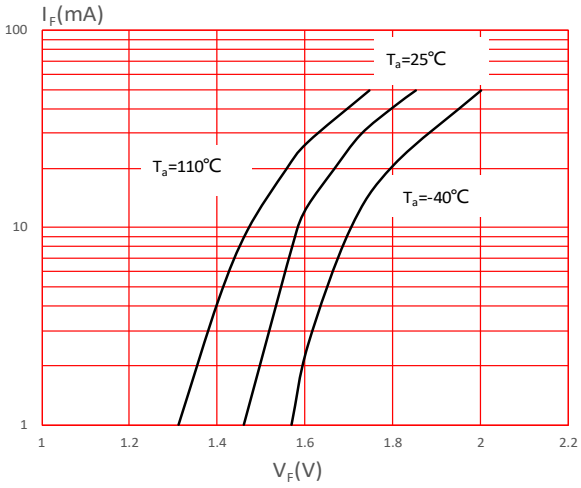


FIG.2: High Level Output Current vs. Ambient Temperature

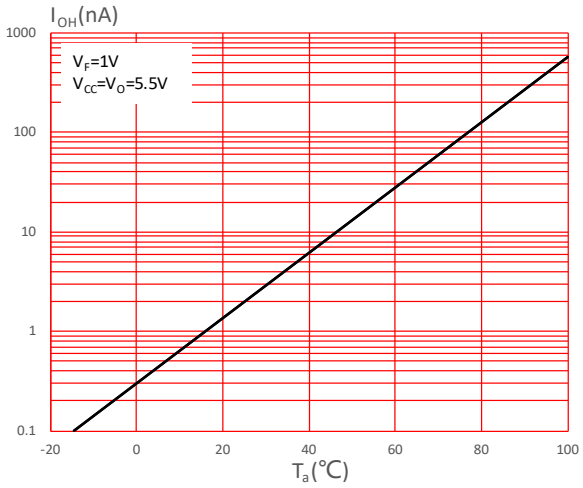


FIG.3: Output Current vs. Forward Current

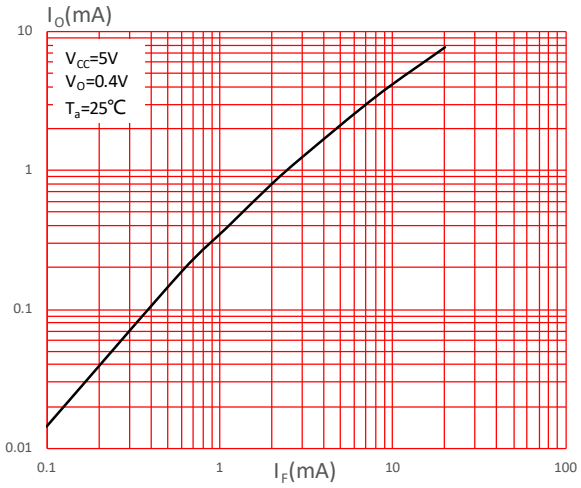


FIG.4: Normalized Current Transfer Ratio vs. Forward Current

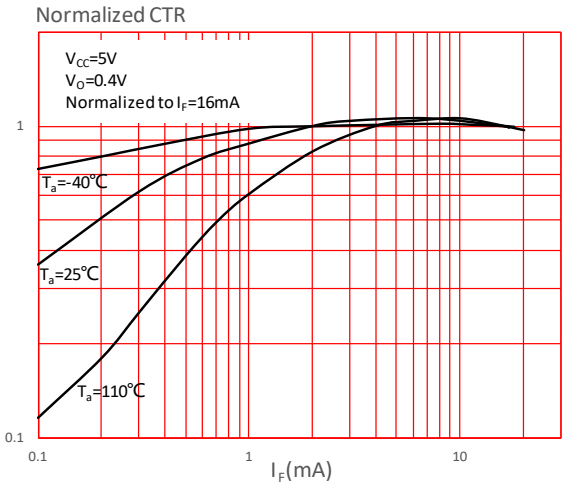


FIG.5: Normalized Current Transfer Ratio vs. Ambient Temperature

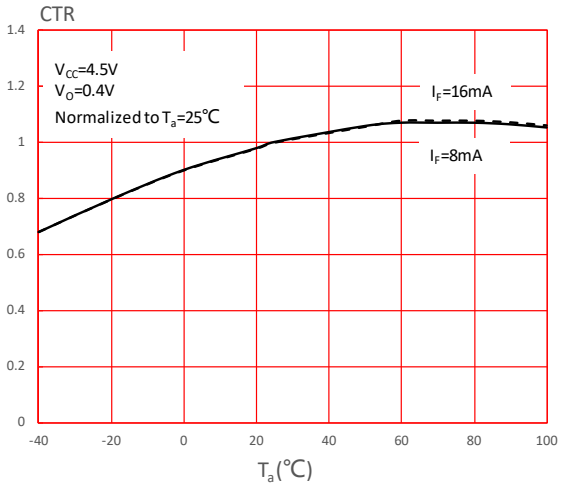


FIG.6: Output Current vs. Output Voltage

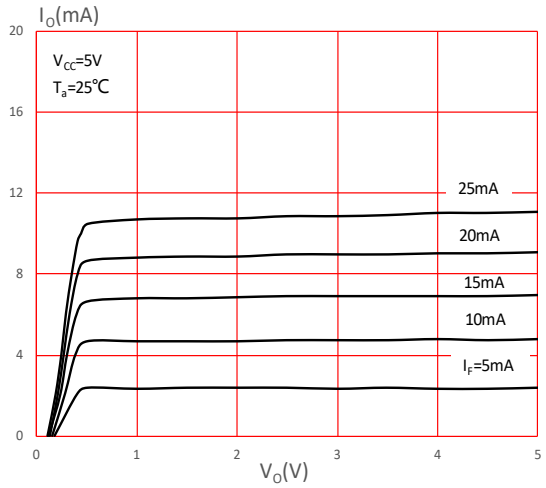


FIG.7: Low Level Output Voltage vs. Ambient Temperature

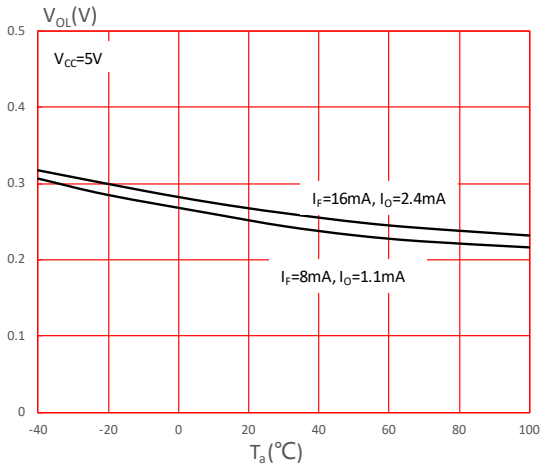


FIG.8: Propagation Delay vs. Load Resistance

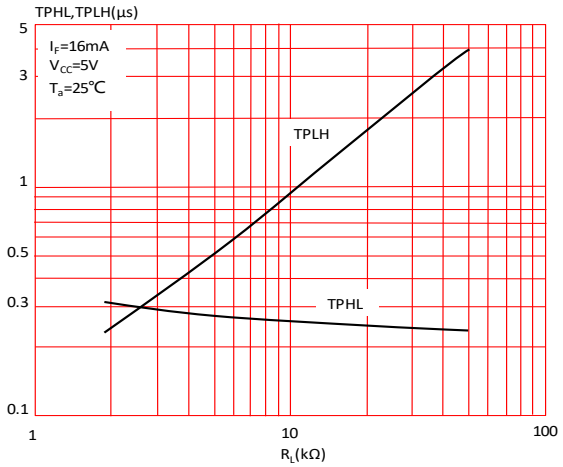
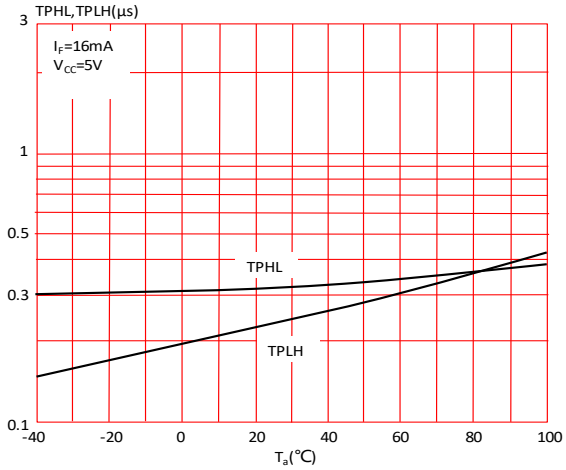
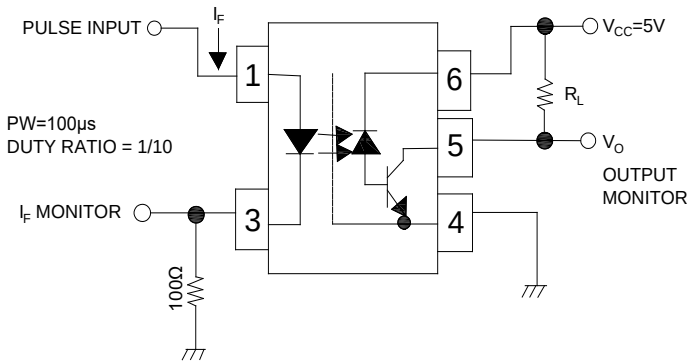


FIG.9: Propagation Delay vs. Ambient Temperature



TEST CIRCUITS

Fig.10: Switching Time Test Circuit and Waveform



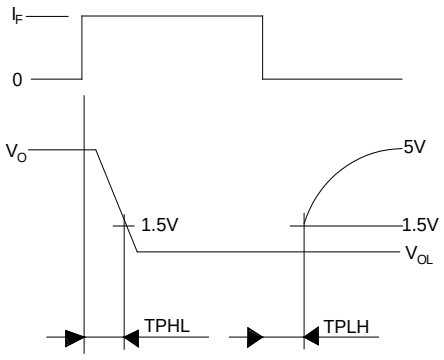
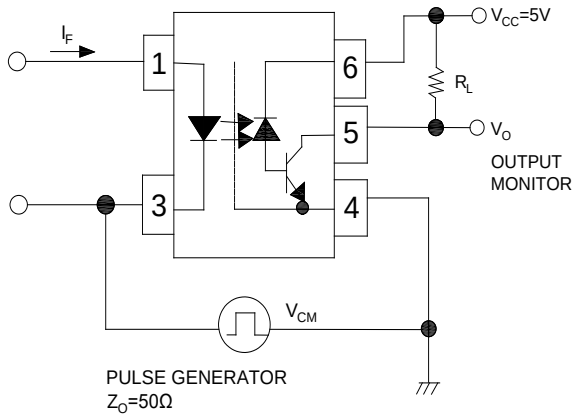
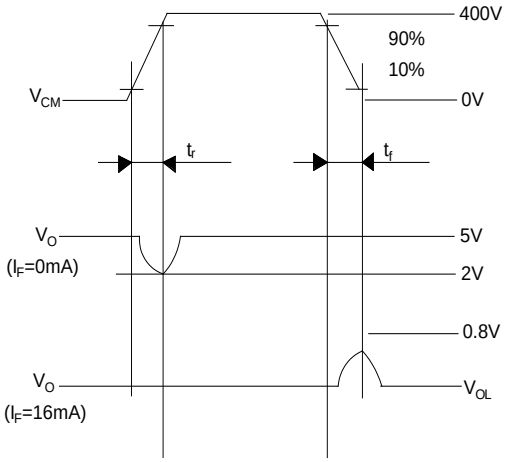
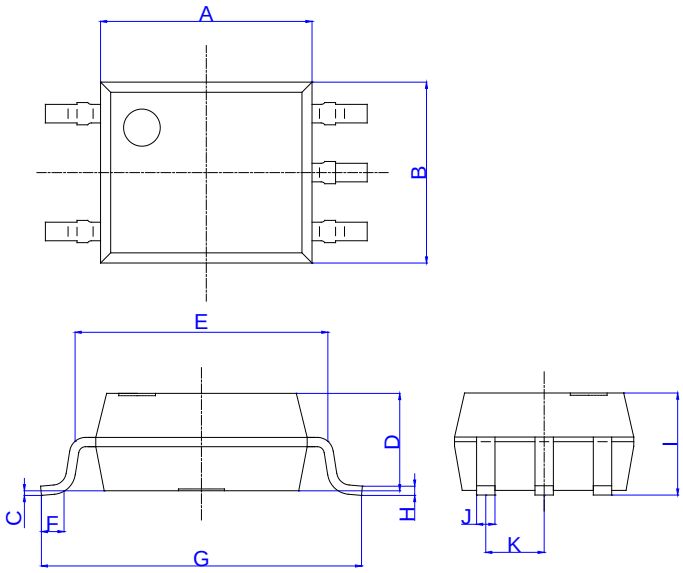


Fig.11: CMTI Test Circuit and Waveform



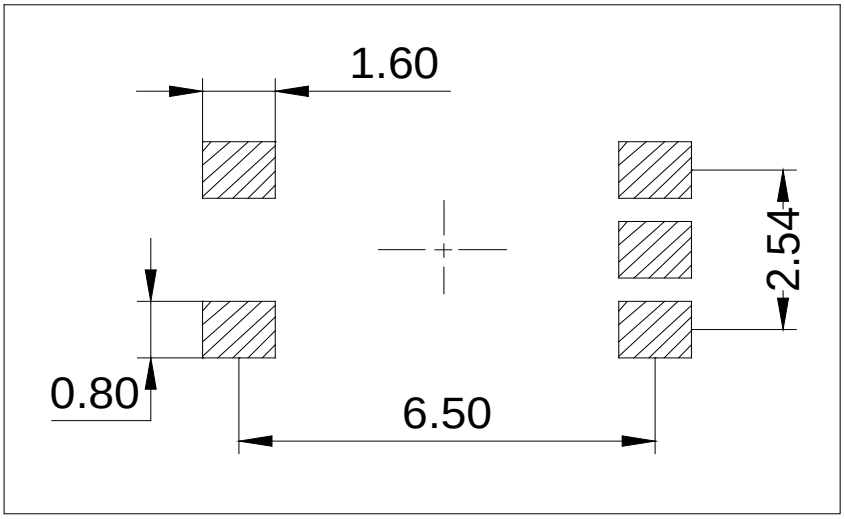


Package Dimension (Unit: mm)



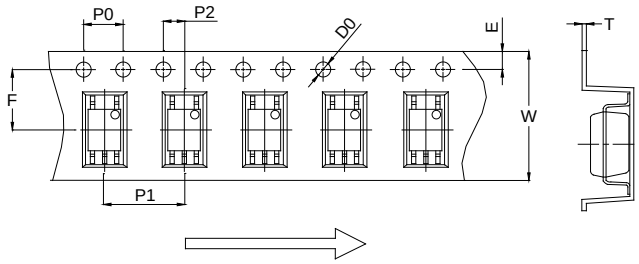
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.80	0.173		0.189
B	3.60		4.20	0.142		0.165
C	0.00		0.20	0.000		0.008
D	1.90		2.30	0.075		0.091
E	5.00		5.60	0.197		0.220
F	0.34		0.94	0.013		0.037
G	6.70		7.30	0.264		0.287
H	0.10		0.30	0.004		0.012
I	2.00		2.40	0.079		0.094
J	0.25		0.55	0.010		0.022
K	1.02		1.52	0.040		0.060

RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)



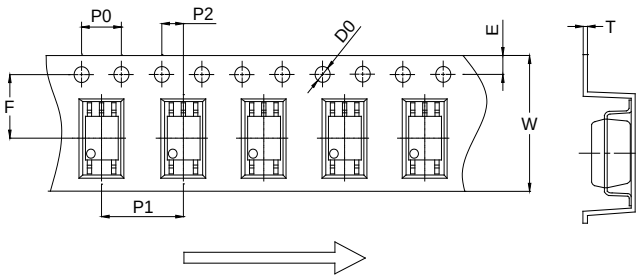
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option T1



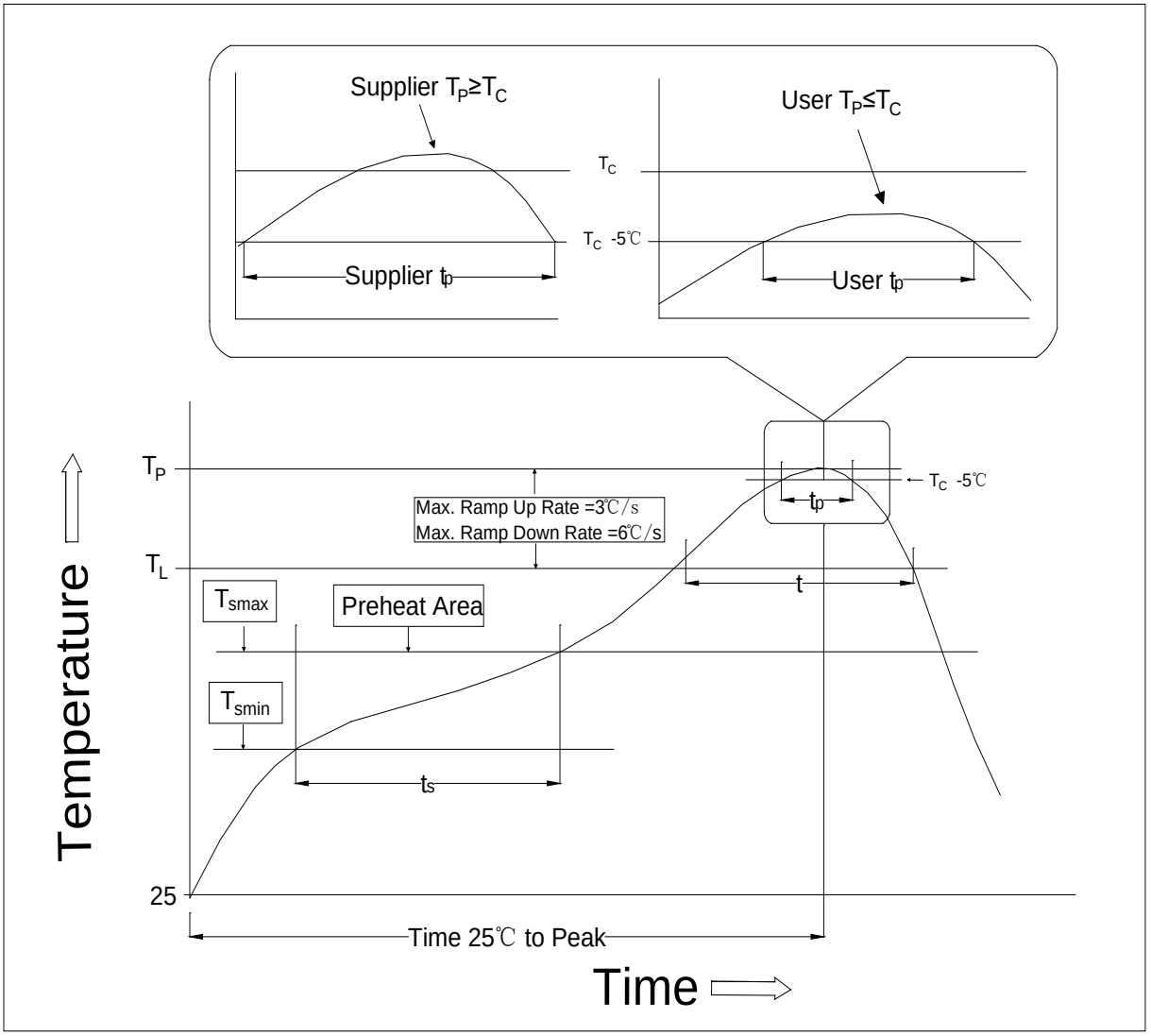
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	4.40	4.50	4.60	0.173	0.177	0.181
T	0.25	0.30	0.35	0.010	0.012	0.014
W	11.90	12.00	12.30	0.469	0.472	0.484

Option T2



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	4.40	4.50	4.60	0.173	0.177	0.181
T	0.25	0.30	0.35	0.010	0.012	0.014
W	11.90	12.00	12.30	0.469	0.472	0.484

REFLOW INFORMATION



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100℃	150℃
Temperature Max. (Tsmax)	150℃	200℃
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3℃/second max.	3℃/second max.
Liquidus Temperature (TL)	183℃	217℃
Time (tL) Maintained Above (TL)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235℃+0℃/-5℃	260℃+0℃/-5℃
Time (tP) within 5℃ of 260℃	10 seconds	10 seconds
Ramp-down Rate (TP to TL)	3-6℃/second	3-6℃/second
Time 25℃ to Peak Temperature	6 minutes max.	8 minutes max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1

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